

SN54ABT2827, SN74ABT2827 10-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS648 – DECEMBER 1995

- Output Ports Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-II B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

These 10-bit buffers or bus drivers provide a high-performance bus interface for wide data-paths or buses carrying parity.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all ten outputs are in the high-impedance state. The 'ABT2827 provide true data at their outputs.

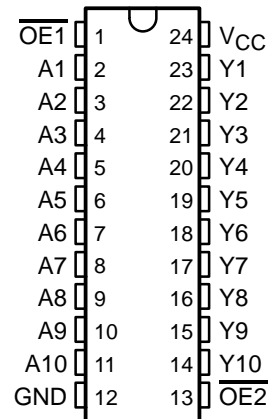
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include 25- Ω series resistors to reduce overshoot and undershoot.

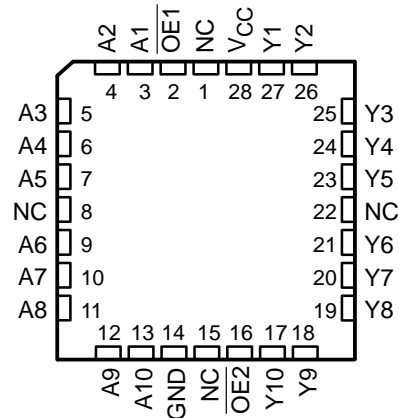
The SN74ABT2827 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT2827 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT2827 is characterized for operation from -40°C to 85°C .

SN54ABT2827 . . . JT PACKAGE
SN74ABT2827 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT2827 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



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**TEXAS
INSTRUMENTS**

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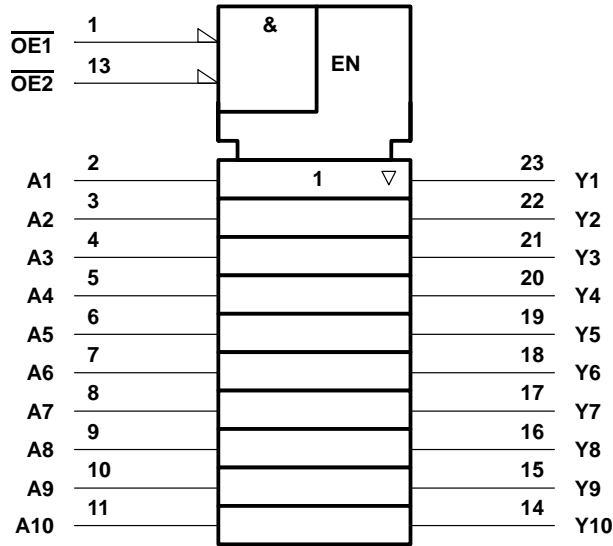
SN54ABT2827, SN74ABT2827
10-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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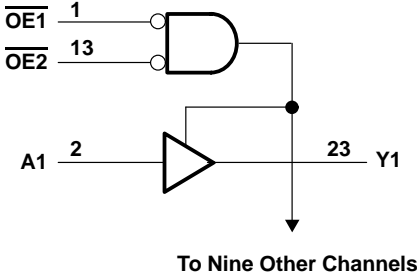
FUNCTION TABLE

INPUTS			OUTPUT Y
OE1	OE2	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT2827	96 mA
SN74ABT2827	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}\text{C}$ (in still air) (see Note 2): DB package	0.65 W
DW package	1.7 W
NT package	1.3 W
Storage temperature range, T_{stg}	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ABT2827		SN74ABT2827		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–12		–12	mA
I_{OL}	Low-level output current		12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$T_A = 25^\circ\text{C}$			SN54ABT2827		SN74ABT2827		UNIT
					MIN	MAX	MIN	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			–1.2		–1.2		–1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -1\text{ mA}$			2.5		2.5		2.5	V
	$V_{CC} = 5\text{ V}$, $I_{OH} = -1\text{ mA}$			3		3		3	
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$		2.4		2.4		2.4	
		$I_{OH} = -12\text{ mA}$		2		2		2	
V_{OL}	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 12\text{ mA}$		0.8		0.8		0.8	V
I_I	$V_{CC} = 0\text{ to }5.5\text{ V}$, $V_I = V_{CC}\text{ or GND}$			± 1		± 1		± 1	μA
I_{OZH}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$			10^\ddagger		10		10^\ddagger	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$, $V_O = 0.5\text{ V}$			-10^\ddagger		–10		-10^\ddagger	μA
I_{off}	$V_{CC} = 0$, $V_I\text{ or }V_O \leq 4.5\text{ V}$			± 100				± 100	μA
I_{CEX}	$V_{CC} = 5.5\text{ V}$, $V_O = 5.5\text{ V}$	Outputs high		50		50		50	μA
I_O^\S	$V_{CC} = 5.5\text{ V}$, $V_O = 2.5\text{ V}$			–50 –140 –225 ‡	–50	–225 ‡	–50	–225 ‡	mA
I_{CC}	$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$	Outputs high		80 250		250		250	μA
		Outputs low		35 40 ‡		40 ‡		40 ‡	mA
		Outputs disabled		80 250		250		250	μA
ΔI_{CC}^\P	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at $V_{CC}\text{ or GND}$	Outputs enabled		1.5		1.5		1.5	mA
		Outputs disabled		50		50		50	μA
		Control inputs		1.5		1.5		1.5	mA
C_i	$V_I = 2.5\text{ V or }0.5\text{ V}$			4					pF
C_o	$V_O = 2.5\text{ V or }0.5\text{ V}$			8.5					pF

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This data sheet limit may vary among suppliers.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT2827, SN74ABT2827

10-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

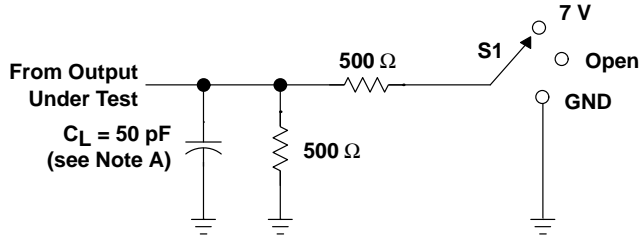
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABT2827		SN74ABT2827		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.1	3.3	5.1	1.1	5.6	1.1	5.5	ns
t_{PHL}			1.1	2.7	4.5	1.1	5.2	1.1	5.1	
t_{PZH}	\overline{OE}	Y	1	4	5.9	1	6.8	1	6.7	ns
t_{PZL}			1	4.2	6.8	1	8	1	7.8	
t_{PHZ}	\overline{OE}	Y	2	5.3	6.7	2	7.4	2	7.2	ns
t_{PLZ}			1.3	4.8	7.2	1.3	8.5	1.3	7.5	

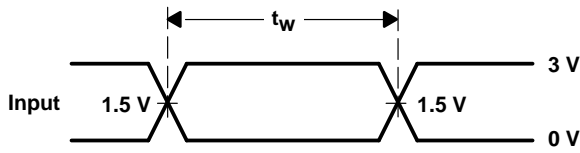
† All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION

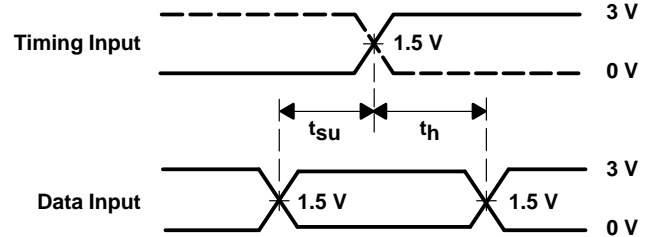


LOAD CIRCUIT FOR OUTPUTS

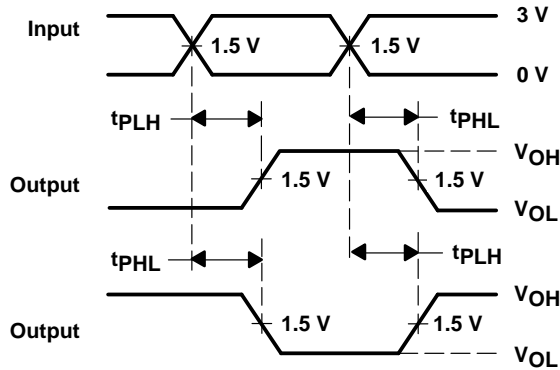
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



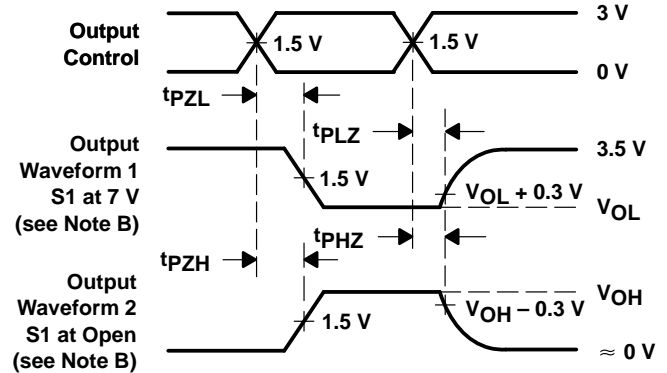
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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